



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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**DZ37082D0L**

Silicon epitaxial planar type

For surge absorption circuit  
 DZ3S082D in SSSMini3 type package

■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol:03

■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

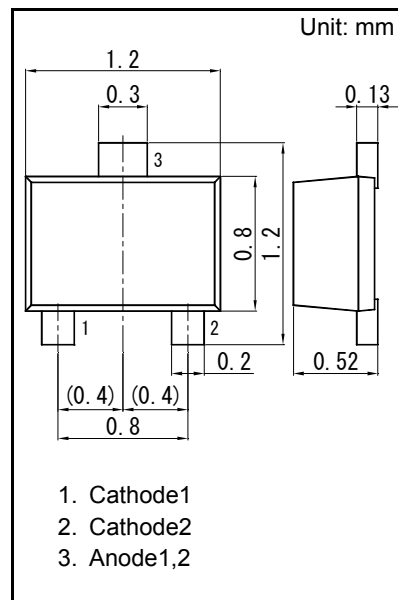
Parameter	Symbol	Rating	Unit
Total power dissipation <sup>*1</sup>	PT	150	mW
Electrostatic discharge <sup>*2</sup>	ESD	±10	kV
Junction temperature	T <sub>j</sub>	150	°C
Operating ambient temperature	T <sub>opr</sub>	-40 to +85	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

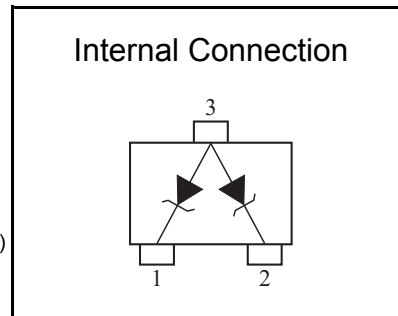
(2 Diode total)

Solder in ( Recommended land pattern)

\*2: Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)



Panasonic	SSSMini3-F2-B
JEITA	SC-105AA
Code	SOT-723



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA			1.0	V
Zener voltage <sup>*1, *2</sup>	V <sub>Z</sub>	I <sub>Z</sub> = 5 mA	7.79		8.61	V
Zener operating resistance	R <sub>Z</sub>	I <sub>Z</sub> = 5 mA			30	Ω
Zener rise operating resistance	R <sub>ZK</sub>	I <sub>Z</sub> = 0.5 mA			60	Ω
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5 V			0.1	μA
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	I <sub>Z</sub> = 5 mA		4.8		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

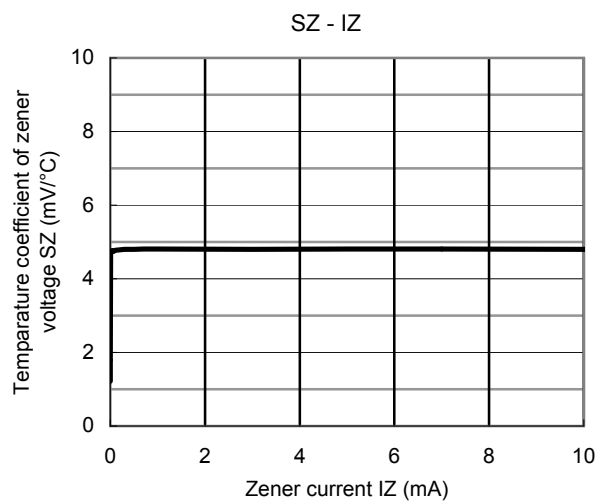
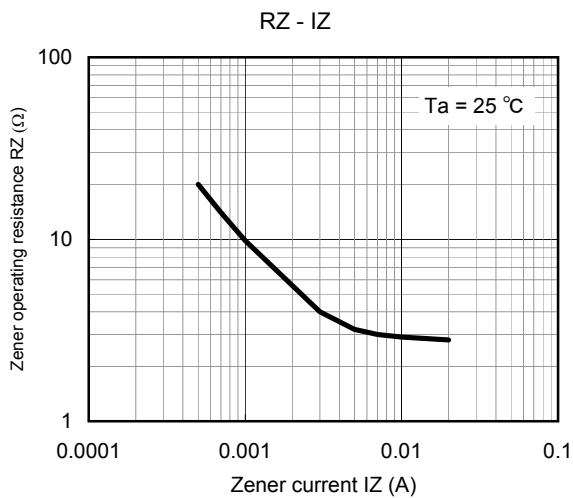
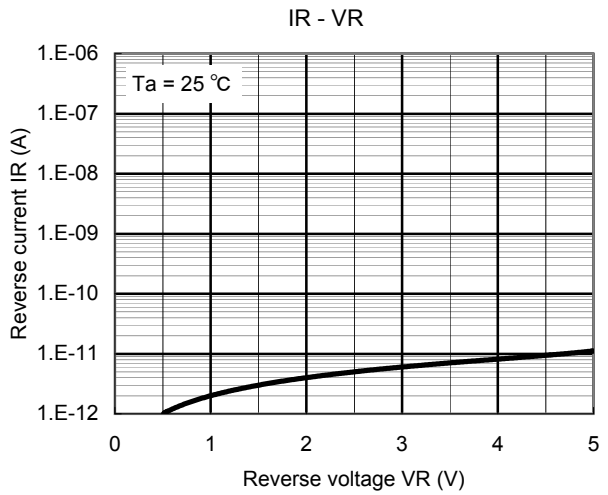
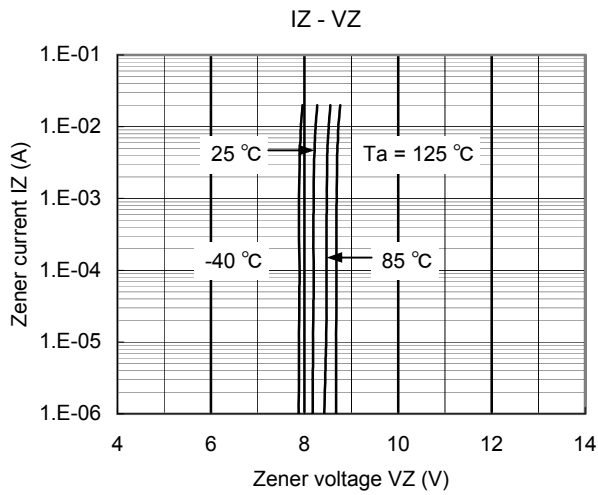
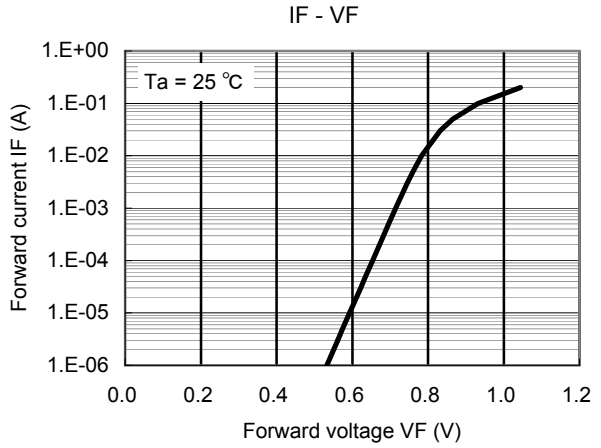
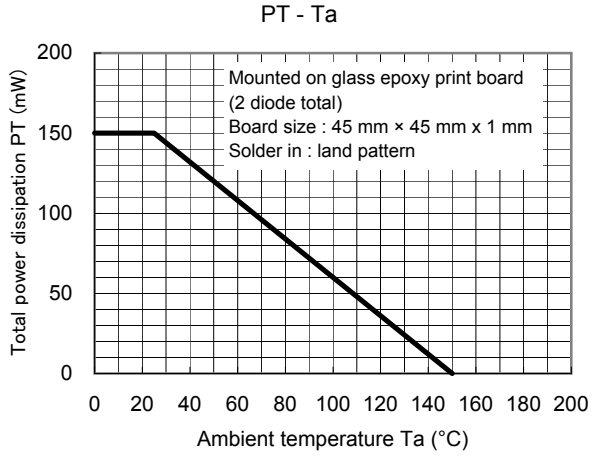
2. \*1: The temperature must be controlled 25°C for V<sub>Z</sub> measurement.

V<sub>Z</sub> value measured at other temperature must be adjusted to V<sub>Z</sub> (25°C)

\*2: V<sub>Z</sub> guaranteed 20 ms after current flow.

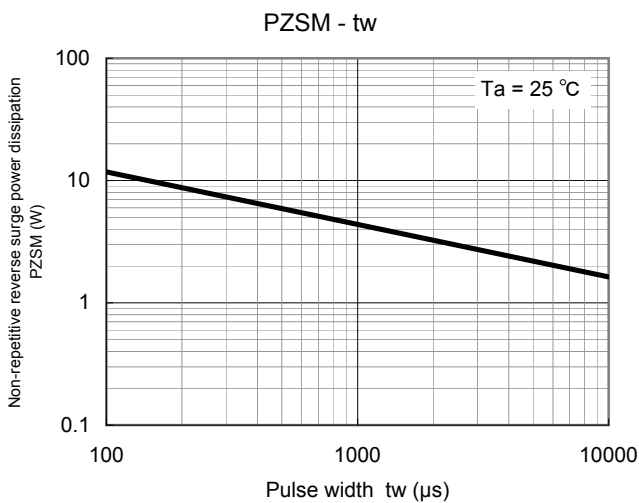
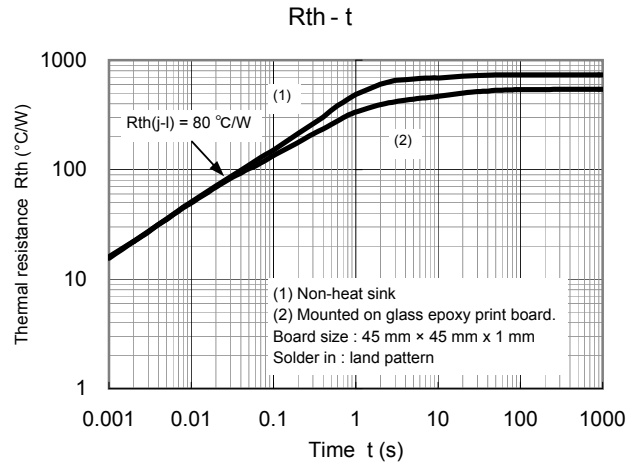
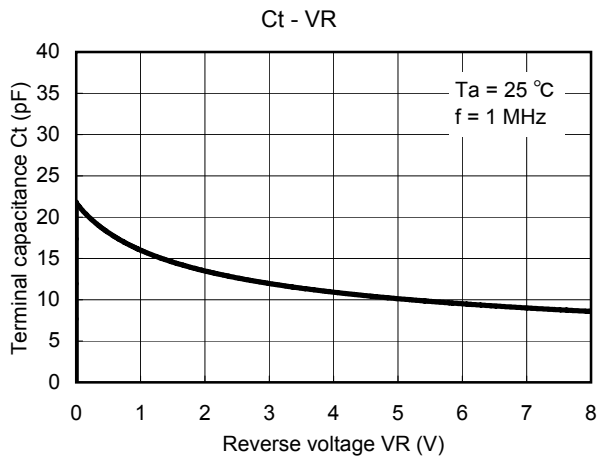
\*3: T<sub>j</sub> = 25°C to 150°C

Technical Data ( reference )





Technical Data ( reference )





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